

HSF

TECHNICAL SPECS:

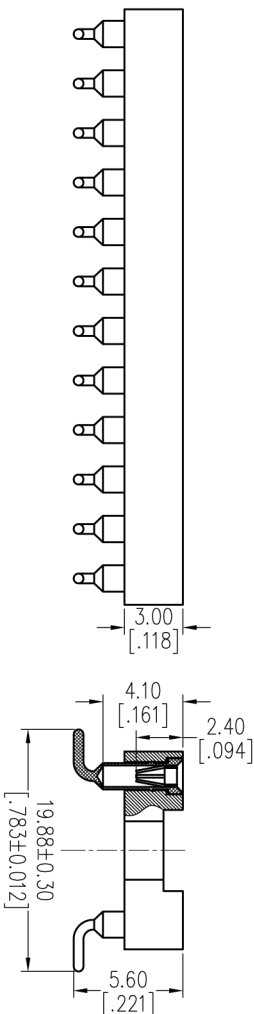
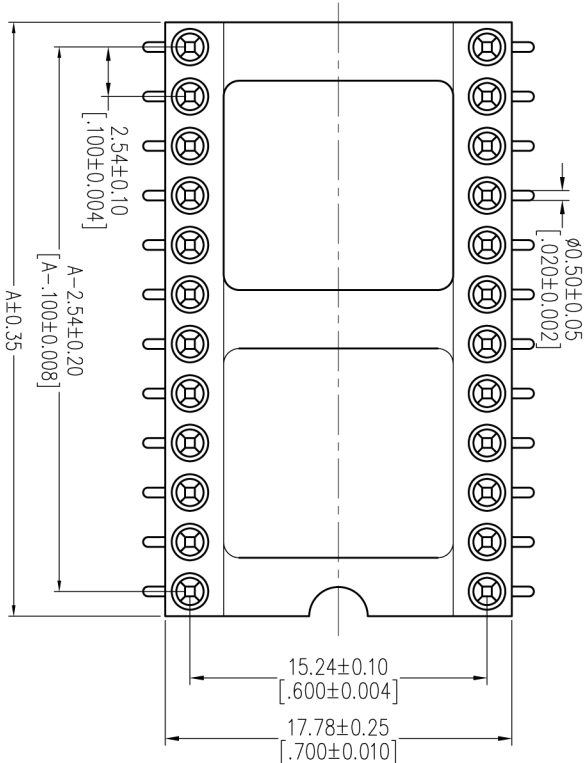
Current Rating: 1.0AMP
 Contact Resistance: 10m Ω Max
 Dielectric Strength: Min 1000Vrms
 Mechanical Life: Min 100 cycles
 Mating Pin: ϕ 0.40 to ϕ 0.56mm
 Forces: (polished steel gauge ϕ 0.43mm)
 Insertion: 200g Max/Pin, Withdrawl: 60g Min/Pin
 Operation Temperature: -40°C to +105°C

Sleeve: Brass CuZn36Pb3(C36000), Sn over Ni
 Contact Chip(4 finger): BeCu(C17200), Au or Sn over Ni
 Insulator Material: PPS+30%G.F(U.L94V-0)
 24P~32P Insulators with center one bar
 36P~48P Insulators with center two bar

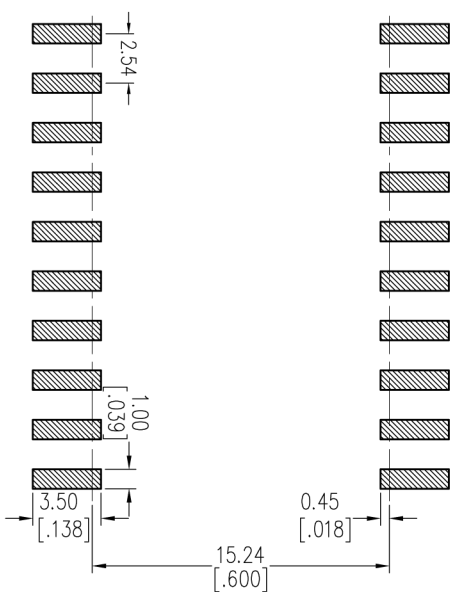
Ordering Information

7110-302 XX M XX 074 X 1

Row of Pitch No. of Pin Contact Plating Packing
 2=15.24mm See tab S0=Gold Flash/Tin T=Tube
 S3=10u"Gold/Tin R=Tape&Reel
 S4=15u"Gold/Tin
 S5=30u"Gold/Tin
 SN=Tim



Recommended P.C.B Layout(Top Side)
 (PCB BOARD TOLERANCE \pm 0.05)



Dimensional & Ordering Information

No. of Poles	Part No.	Dim
24	7110-30224MXX074X1	30.48
28	7110-30228MXX074X1	35.56
32	7110-30232MXX074X1	40.64
36	7110-30236MXX074X1	45.72
40	7110-30240MXX074X1	50.80
42	7110-30242MXX074X1	53.34
48	7110-30248MXX074X1	60.96

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REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
A0	2012/11/02	NEW		XX \pm 0.40	JYHuang	2012/11/02	mm	A4	7110-302XXMXX074X1
				X.XX \pm 0.25	CHECK	DATE	SIZE	A4	TITLE: IC SOCKET SMT H=3.0 L=7.43 Row of Pitch 15.24mm
				X.XXX \pm 0.15			SHEET	1/1	
				Angle \pm 3'	APPROVE	DATE	PROJ.		Customer NO.
				DIM TOL					